On-chip Temperature Compensation and Calibration

Figure 3. illustrates both the Differential/Gauge and the Absolute Sensing Chip in the basic chip carrier (Case 867). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm. (For use of the MPX5700D in a high-pressure cyclic application, consult the factory.)

The MPX5700 series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 2. shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in . The output will saturate outside of the specified pressure range.

shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

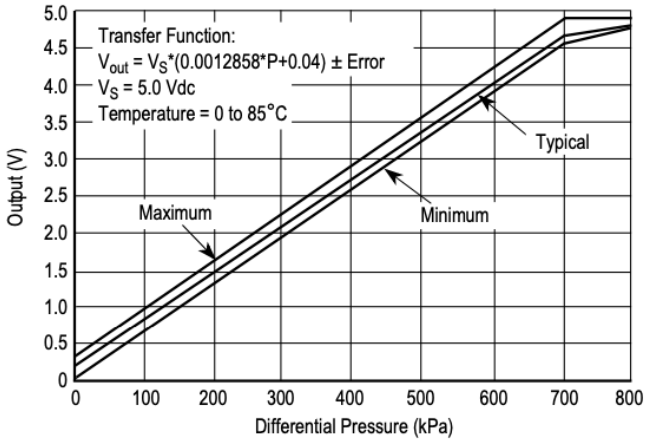

Figure 2. Output vs. Pressure Differential

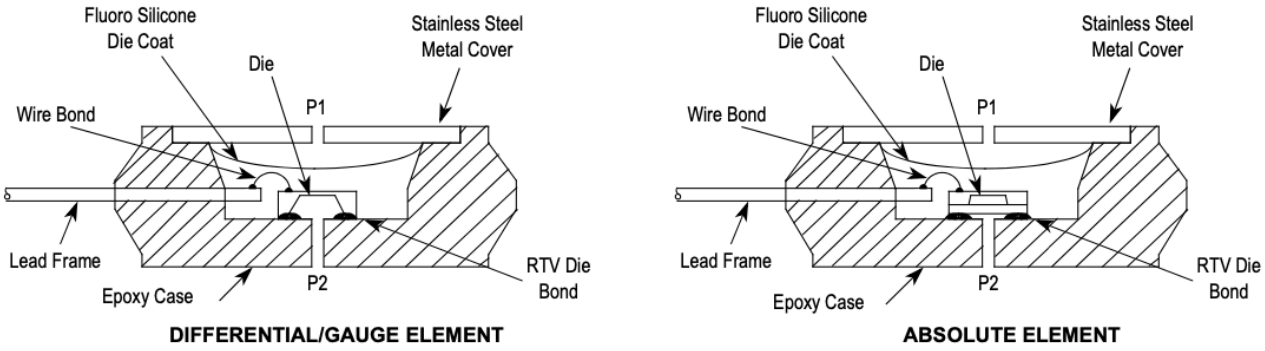

Figure 3. Cross-Sectional Diagrams (not to scale)

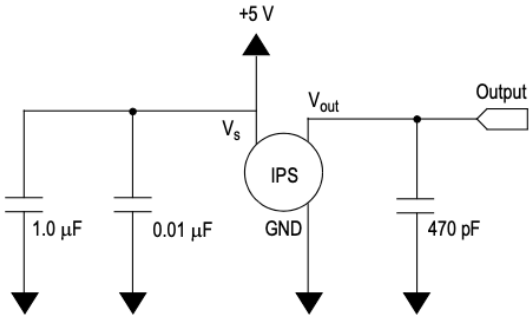

Figure 4. Recommended Power Supply Decoupling and Output Filtering (For additional output filtering, please refer to Application Note AN1646)